

ESD351 0402パッケージでクランプ電圧の低い 1チャンネル、30kV ESD保護ダイオード

1 特長

- IEC 61000-4-2 レベル4 ESD保護
 - 接触放電 $\pm 30\text{kV}$
 - 空気ギャップ放電 $\pm 30\text{kV}$
- IEC 61000-4-4 EFT保護
 - 80A (5/50ns)
- IEC 61000-4-5 サージ保護
 - 6A (8/20 μs)
- IO容量: 1.8pF (標準値)
- DC降伏電圧: 4.5V (最小値)
- 低いリーク電流: 0.1nA (標準値)
- 非常に低いESDクランプ電圧
 - 16A TLPで6.5V (I/OからGNDへ)
 - R_{DYN} : 0.1 Ω (I/OピンからGNDへ)
- 工業用温度範囲: -40 $^{\circ}\text{C}$ ~+125 $^{\circ}\text{C}$
- 業界標準の0402パッケージ (DFN1006P2)

2 アプリケーション

- 最終製品
 - ウェアラブル
 - 産業用およびサービス用ロボット
 - ラップトップおよびデスクトップPC
 - モバイルおよびタブレット
 - セットトップ・ボックス
 - DVRおよびNVR
 - TVおよびモニタ
 - EPOS (電子販売時点情報管理)
- インターフェイス
 - USB 2.0/1.1
 - GPIO
 - プッシュボタン
 - オーディオ

3 概要

ESD351は単方向TVS ESD保護ダイオードで、低い動的抵抗 R_{DYN} と、低いクランプ電圧が特長です。ESD351は、IEC 61000-4-2標準に従い、最高30kVのESD衝撃(接触および空中)を放散できることが規定されています。動的抵抗(0.1 Ω)とクランプ電圧(16A TLPで6.5V)が非常に低いため、過渡事象に対するシステム・レベルの保護が保証されます。このデバイスの容量は1.8pF(標準値)で、USB 2.0などのインターフェイスの保護に理想的です。

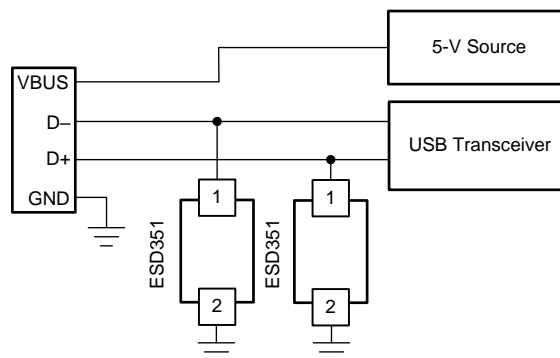
ESD351は、業界標準の0402 (DPY/DFN1006P2)パッケージで供給されます。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
ESD351	X1SON (2)	0.60mm \times 1.00mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

代表的なUSB 2.0アプリケーションの回路図



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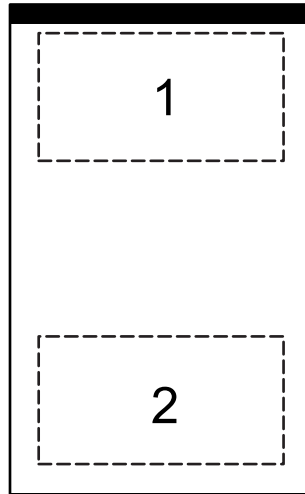
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4 改訂履歴

日付	リビジョン	注
2018年7月	*	初版

5 Pin Configuration and Functions

DPY Package
2-Pin X1SON
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	IO	I/O	ESD Protected Channel. Connect this pin to the line being protected.
2	GND	GND	Connect this pin to Ground

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Electrical Fast Transient	IEC 61000-4-4 Peak Current at 25 °C		80	A
Surge Pulse	IEC 61000-4-5 Surge (tp 8/20 μs) Peak Power at 25 °C		36	W
	IEC 61000-4-5 Surge (tp 8/20 μs) Peak Current at 25 °C		6	A
T _A	Operating free-air temperature	–40	125	°C
T _{stg}	Storage temperature	–65	155	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings -JEDEC Specifications

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, allpins ⁽¹⁾	±2500
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 ESD Ratings - IEC Specifications

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	IEC 61000-4-2 Contact Discharge, all pins	±30000
		IEC 61000-4-2 Air Discharge, all pins	±30000

6.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{IN}	Input voltage	0		3.6	V
T _A	Operating Free Air Temperature	–40		125	°C

6.5 Thermal Information

THERMAL METRIC ⁽¹⁾		ESD351	UNIT
		DPY (X1SON)	
		2 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	409.4	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	216.8	°C/W
R _{θJB}	Junction-to-board thermal resistance	140.4	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	81.4	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	140.0	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

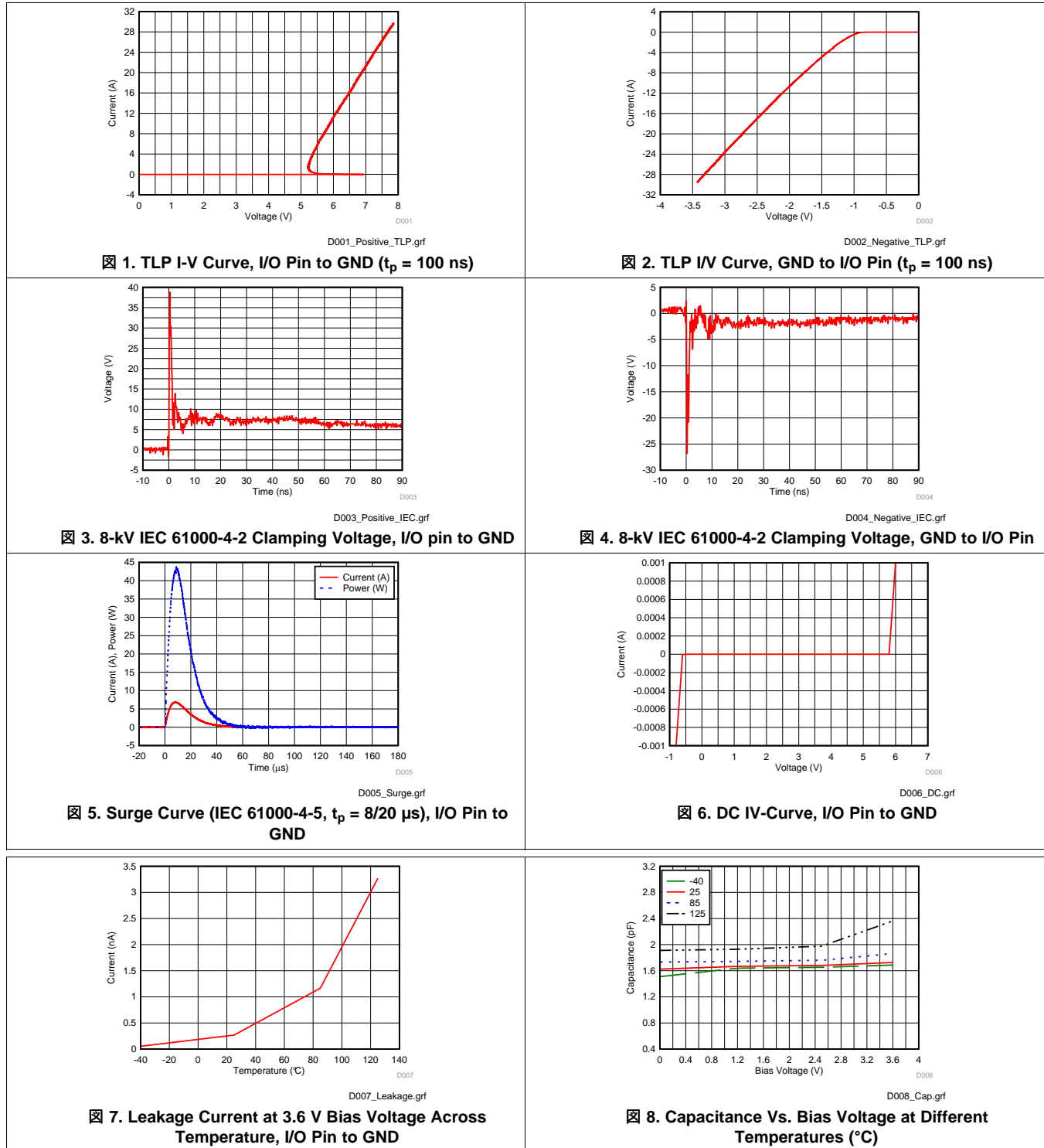
6.6 Electrical Characteristics

At TA = 25°C unless otherwise noted

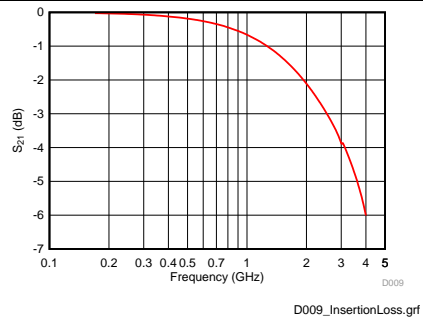
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{RWM}	Reverse stand-off voltage	I _{IO} < 50 nA, across operating temperature range			3.6	V
I _{LEAKAGE}	Leakage current at 3.6 V	V _{IO} = 3.6 V, I/O to GND		0.1	10	nA
V _{BRF}	Breakdown voltage, I/O to GND ⁽¹⁾	I _{IO} = 1 mA	4.5		7.5	V
V _{FWD}	Forward Voltage, GND to I/O ⁽¹⁾	I _{IO} = 1 mA		0.8		V
V _{HOLD}	Holding voltage, I/O to GND ⁽²⁾	I _{IO} = 1 mA		5.1		V
V _{CLAMP}	Clamping voltage	I _{PP} = 6 A (8/20 μs Surge), I/O to GND		6.1		V
		I _{PP} = 16 A (100 ns TLP), I/O to GND		6.5		V
		I _{PP} = 16 A (100 ns TLP), GND to I/O		2.5		V
R _{DYN}	Dynamic resistance	I/O to GND, 100 ns TLP, between 10 to 20 A I _{PP}		0.1		Ω
		GND to I/O, 100 ns TLP, between 10 to 20 A I _{PP}		0.08		
C _{LINE}	Line capacitance, IO to GND	V _{IO} = 0 V, V _{p-p} = 30 mV, f = 1 MHz		1.8	2.2	pF

- (1) V_{BRF} and V_{BRR} are defined as the voltage obtained at 1 mA when sweeping the voltage up, before the device latches into the snapback state
- (2) V_{HOLD} is defined as the voltage when 1 mA is applied, after the device has successfully latched into the snapback state.

6.7 Typical Characteristics



Typical Characteristics (continued)



9. Insertion Loss Vs. Frequency

7 Detailed Description

7.1 Overview

The ESD351 is a uni-directional ESD Protection Diode with 30 kV IEC 61000-4-2 level (Contact and Air) with ultra-low clamping voltage in a 1 mm × 0.6 mm package. The ultra-low clamping makes this device capable of protecting any ESD-sensitive pins.

7.2 Functional Block Diagram



7.3 Feature Description

ESD351 provides ESD protection up to ± 30 -kV contact and ± 30 -kV air gap per IEC 61000-4-2 standard. During an ESD event, ESD diode connected to the I/O pin turns on and diverts the current to ground. Additionally, ESD351 also provides protection against IEC 61000-4-5 Surge currents up to 6 A (8/20 μ s waveform) and up to 80 A per IEC 61000-4-4 (5/50 ns waveform, 4 kV with 50- Ω impedance) electrical fast transient (EFT) standard. The capacitance between the I/O pin and ground is 1.8 pF (typical) and 2.2 pF (maximum). The device features a low leakage current of 0.1 nA (typical) and 50 nA (maximum, across operating temperature range) with a bias of 3.6 V. The ESD diode at the I/O pin protects the ESD-sensitive devices by clamping the voltage to a low value of 6.5 V ($I_{PP} = 16$ A 100 ns TLP). The layout of this device makes it simple and easy to add protection to an existing layout. The packages offers flow-through routing, requiring minimal modification to an existing layout.

7.4 Device Functional Modes

The ESD351 is a passive integrated circuit that triggers when voltages are above V_{BRF} or below V_{FWD} . During ESD events, voltages as high as ± 30 kV (contact or air) can be directed to ground via the internal diode network. When the voltages on the protected line fall below the trigger levels of ESD351 (usually within 10s of nano-seconds) the device reverts to passive.

8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The ESD351 is a diode type TVS which is used to provide a path to ground for dissipating ESD events on high-speed signal lines between a human interface connector and a system. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. This is the voltage presented to the protected IC. The low R_{DYN} of the triggered TVS holds this voltage, V_{CLAMP} , to a safe level for the protected IC.

8.2 Typical Application

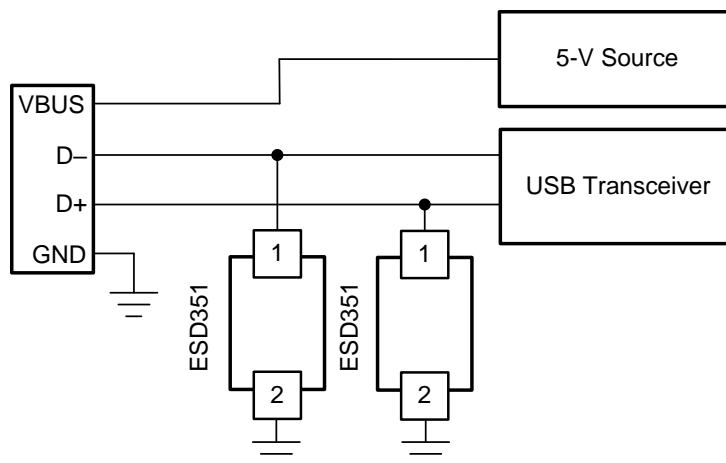


图 10. USB 2.0 ESD Schematic

8.2.1 Design Requirements

For this design example, two ESD351 devices are being used in a USB 2.0 application. This provides a complete ESD protection scheme.

Given the USB 2.0 application, the parameters listed in 表 1 are known.

表 1. Design Parameters

DESIGN PARAMETER	VALUE
Signal range on DP-DM lines	0 V to 3.6 V
Operating frequency on DP-DM lines	up to 240 MHz

8.2.2 Detailed Design Procedure

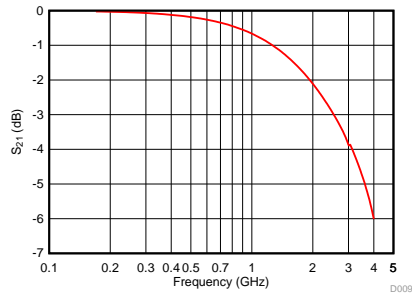
8.2.2.1 Signal Range

The ESD351 supports signal ranges between 0 V and 3.6 V, which supports the USB 2.0 signal pair on the USB 2.0 application.

8.2.2.2 Operating Frequency

The ESD351 has a 1.8 pF (typical) capacitance, which supports the USB 2.0 data rates of 480 Mbps.

8.2.3 Application Curve



D009_InsertionLoss.grf

11. Insertion Loss

9 Power Supply Recommendations

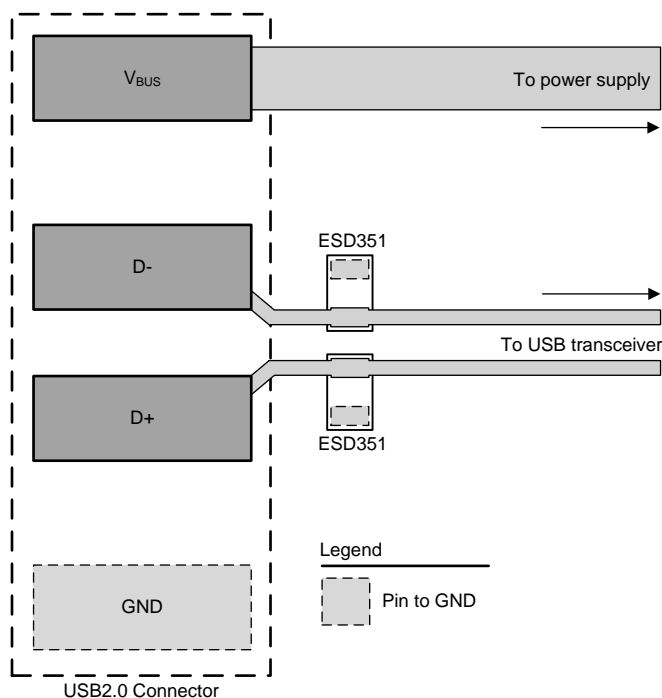
The ESD351 is a passive ESD device so there is no need to power it. Take care not to violate the recommended I/O specification (0 V to 3.6 V) to ensure the device functions properly.

10 Layout

10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
 - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
 - The PCB designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
 - Electric fields tend to build up on corners, increasing EMI coupling.

10.2 Layout Example



12. USB 2.0 ESD Layout

11 デバイスおよびドキュメントのサポート

11.1 ドキュメントのサポート

11.1.1 関連資料

関連資料については、以下を参照してください。

『汎用ESDデバイス評価モジュール』、[SLVUBG5](#)

11.2 ドキュメントの更新通知を受け取る方法

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11.3 コミュニティ・リソース

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11.4 商標

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11.5 静電気放電に関する注意事項



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11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ESD351DPYR	ACTIVE	X1SON	DPY	2	10000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(A5, DE)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

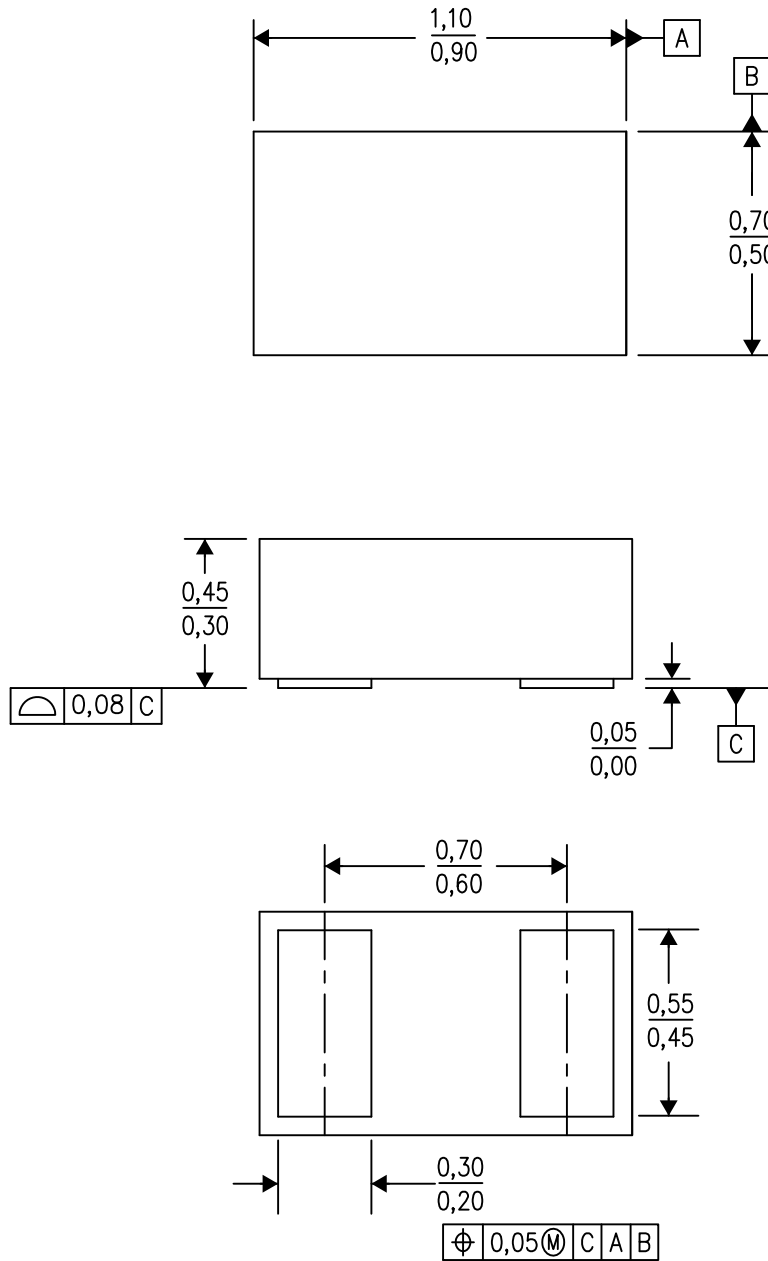
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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DPY (R-PX1SON-N2)

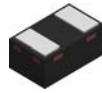
PLASTIC SMALL OUTLINE NO-LEAD



4211012/D 08/14

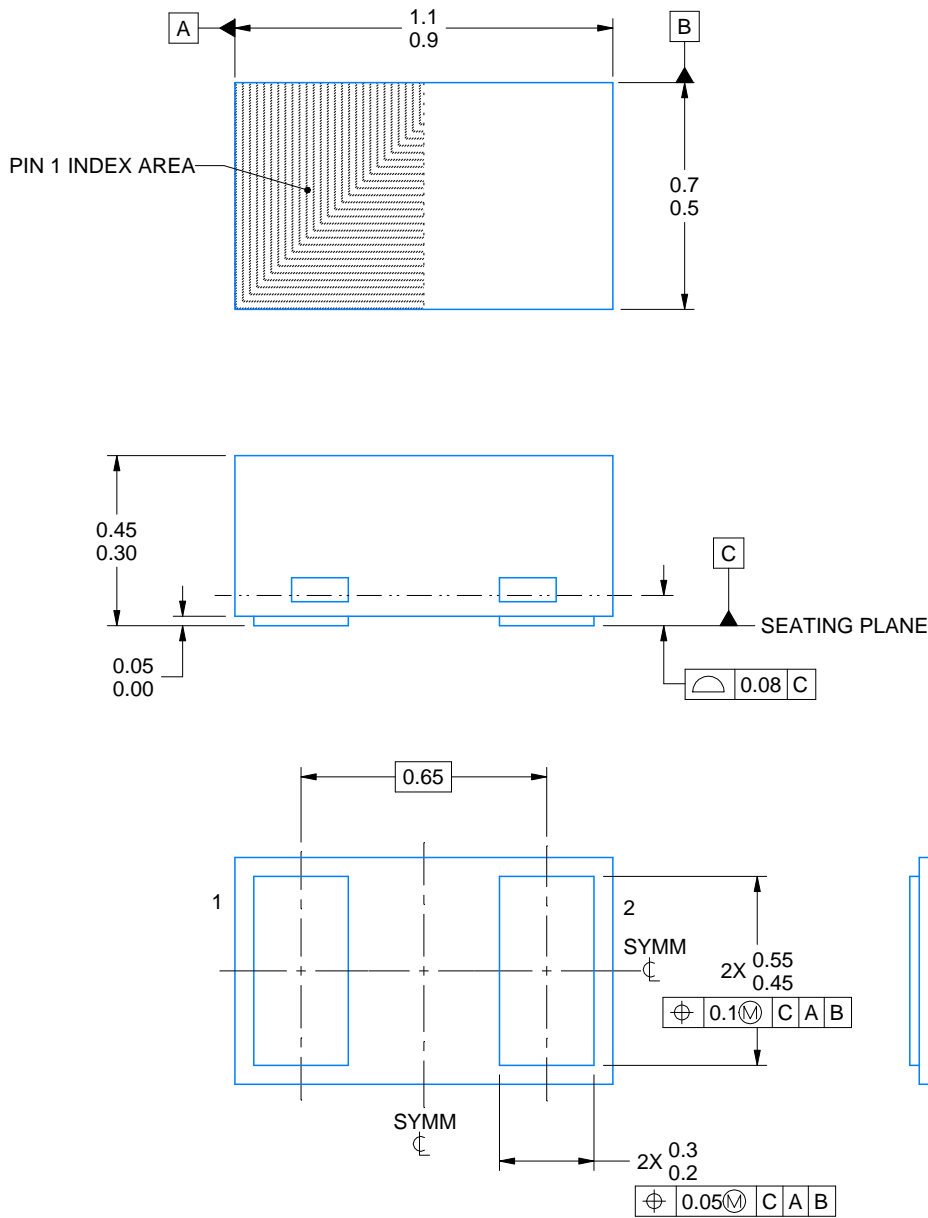
- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.

DPY0002A



PACKAGE OUTLINE
X1SON - 0.45 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4224561/B 03/2021

NOTES:

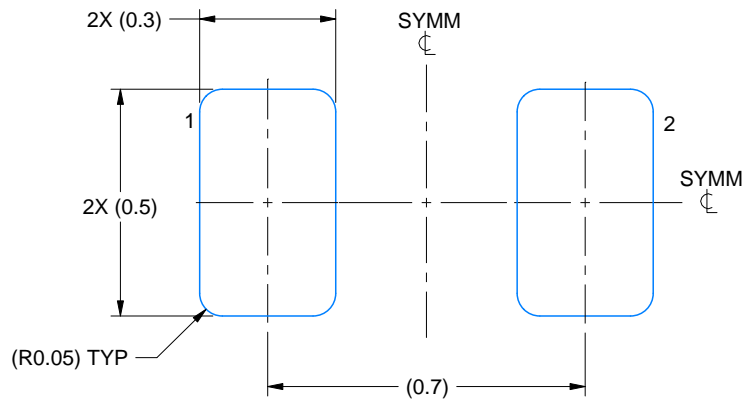
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

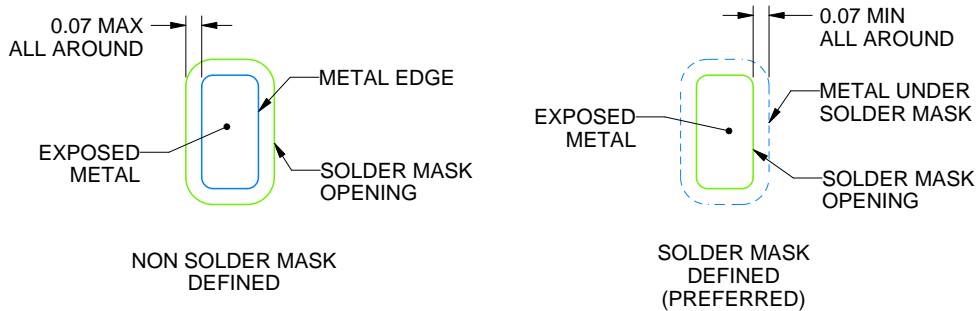
DPY0002A

X1SON - 0.45 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:60X



SOLDER MASK DETAILS

4224561/B 03/2021

NOTES: (continued)

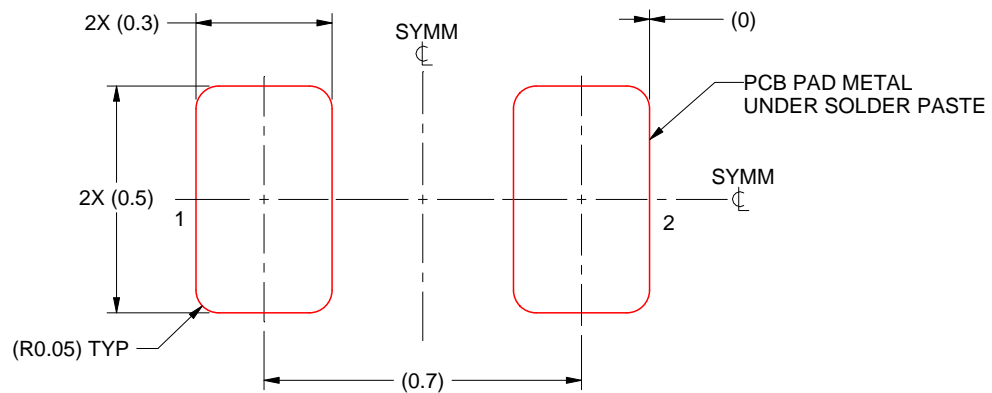
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
4. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DPY0002A

X1SON - 0.45 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:60X

4224561/B 03/2021

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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